

Description: 2.4GHz Ceramic Chip Antenna

Series: Ceramic Chip Antenna

PART NUMBER: W3008G

Features:

- Frequency 2400-2483.5MHz
- Size 3.2 x 1.6 x 1.1mm
- Efficiency >80%
- Gain >1.5dBi
- SMD compatible
- MSL 3

Applications:

- 2.4GHz ISM band radios
- Bluetooth, BLE
- WiFi 2.4GHz
- IoT, M2M devices

All dimensions are in mm / inches

Issue: 1905

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ELECTRICAL SPECIFICATIONS

Antenna Type	Ceramic Chip
Frequency	2400-2483.5MHz
Nominal Impedance	50 Ω
VSWR	<1.6:1
Radiation Pattern	Omni
Gain	>1.5dBi
Efficiency	>80%
Polarization	Linear
Power Withstanding	2W

MECHANICAL SPECIFICATIONS

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	3

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature	-40 / +85
Storage Temperature	-40 / +85
RoHS Compliant	Yes

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MECHANICAL DRAWING





Antenna features		
No.	Terminal Name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm
Antenna is symmetrical. Either of terminals 1 or 2 can be Feed / GND		

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OTHER SPECIFICATIONS

PWB Layout

Typical performance (test board size 80x37 mm, PWB ground clearance area 11.00 x 6.25 mm) Antenna placed 80mm edge center position.





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OTHER SPECIFICATIONS

Ground cleared under antenna, clearance area 11.00 x 6.25 mm

Ground clearance area (11,00 x 6,25 mm)





Opening in bottom/inner ground layers





Opening in other layers (no ground/ RF)



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OTHER SPECIFICATIONS

PWB pad dimensions and antenna position



Pad dimensions in top copper





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OTHER SPECIFICATIONS

Typical Ground via hole placement in PWB layout



Solder resist opening and paste stencil recommendations





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TEST SETUP

All RF parameters measured on 37x80mm evaluation board. Antenna placement on side center position of PCB long edge. Shunt 1.2pF capacitor for matching.



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CHARTS

VSWR







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CHARTS

Radiation Efficiency



XY Plane 0 2400MHz 330 Avg(dBi) = -0.22 Peak(dBi) = 1.17 Avg -3(deg) = 346.5 -10 -15 300 60 2450MHz -20 Avg (dBi) = 0.20 Peak (dBi) = 1.45 -25 Avg -3 (deg) = 359.5 -30 Power (dBm) 2500MHz 35 Avg (dBi) = 0.03 270 -40 90 Peak (dBi) = 1.43 Avg -3 (deg) = 350.5 240 120 210 150 Phi Angle (°) 180 2400MHz _____2450MHz _____2500MHz

Radiation pattern X-Y plane

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CHARTS

Radiation pattern Z-X plane





2450MHz⁰ -10 300 60 Avg (dBi) = -1.60 15 Peak (dBi) = 1.17 -20 Avg -3 (deg) = 359.5 -25 Power (dBm) 2500MHz⁰ 30 Avg (dBi) = -1.74 270 90 Peak (dBi) = 1.22 Avg -3 (deg) = 351.5 0 240 120 210 150 Phi Angle (°) 180

2400MHz -2450MHz -- 2500MHz

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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



Figure 1. Minimum temperature profile recommendation for reflow soldering process

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1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 ℃ for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s



Figure 2. Maximum temperature profile recommendation for reflow soldering process

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PACKAGING



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ROHS

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